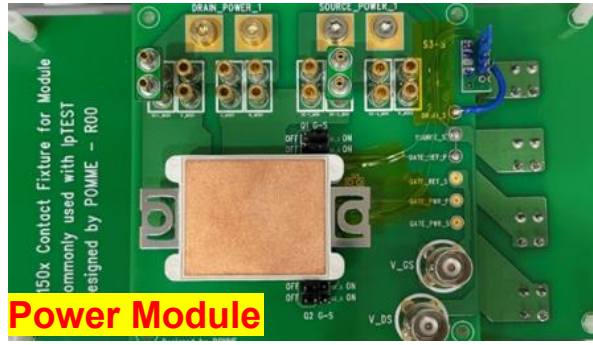
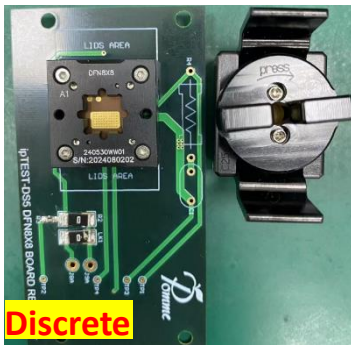




POMME Design test fixture datasheet_v1

AF-WBG-DF for Discrete Fixture

AF-WBG-PC for Power Module Contact Unit







1. Application

- Ducking to Keysight B1505A and B1506A.
- Ducking to ipTEST DC/AC testing station.
- Electrical Operation Range: Voltage +/-0~10kV, Current +/-1pA~1500A.
- Thermal operation range: -55~175°C.
- Package type: TO/ SMT / SMD / Power Module.

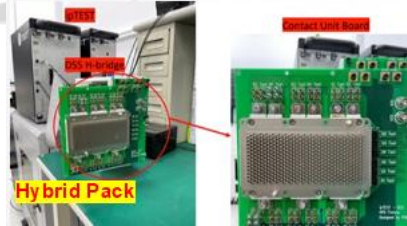


2. Detail Dimensional



2.1 AF-WBG-DF for Discrete Fixture

Discrete	Photo	Note
DFN 8X8		
DFN 5X6		
TO263-2L		

Discrete	Photo	Note
TO252-2L		
TO263-7L		
TO247-3L		
TO247-4L		

2.2 AF-WBG-PC for Power Module Contact Unit

Power Module	Photo	Note
HPD SiC		(750V/1200V) Pin Fin Heatsink 800A~
Easy pack		750V & 1200V 25A & 50A
Easy 1B		

Power Module	Photo	Note
double side cooling		750V & 1200V 400A~550A
Econodual		750V & 1200V 400A~900A



3. Available Test Item

	Power Device		Package	DC characterization	CV characterization	AC characterization	Ruggedness	Temp	Burn-in up to 175°C	EVB (Model) ²⁾	
Engineering support (Characterization)	Silicon	Diode	Discrete, Module ¹⁾	VR,IR,VF	C, Total capacitance	Cj,Reverse recovery	UIS, Diode dv/dt	-55c ~ 200°C	-	Can be supported (DPT, Qg, UIS, SCWT and so on)	
		MOSFET		BV,Ids,Rds(on),Igs,Vth,Vsd	Cgd, Cgs, Cds, Ciss, Coss, Crss	Swiching time, Reverse recovery of body diode, Qg	UIS, MOSFET&Diode dv/dt				
		IGBT		BV,Ice,Vce(sat),Ige,Vth,VF	Cies, Coes, Cres, Cgc, Cge, Cce	Switching loss, Swiching time, Reverse recovery of co-pack diode, Qg	SCWT, Latch testing				
	Silicon carbide	Diode		VR,IR,VF	C, Total capacitance	Cj,Qc,Ec	UIS, Diode dv/dt				Package level (HTGB, HTRB) Wafer level (HTGB, HTRB)
		MOSFET		BV,Ids,Rds(on),Igs,Vth,Vsd	Cgd, Cgs, Cds, Ciss, Coss, Crss	Swiching time, Reverse recovery of body diode	UIS, MOSFET&Diode dv/dt, SCWT				
		HEMT		BV,Ids,Rds(on),Igs,Vth	Cgd, Cgs, Cds, Ciss, Coss, Crss	Swiching time, Switching loss, Qg	Dynamic Ron				
Gallium Nitride											

1) Depending on the module circuit, need to use each fixtures for testing (Pomme can handle it however, should discuss it in advance)

2) Each equipment should consider how to configure handler, especially ac characteristic should be careful to design handler as minimize parasitic components